100L –TQFP (14 x 14 mm)
Pb-Free Package

PACKAGE MATERIAL DECLARATION DATASHEET

Cypress Package Code	AZ	**Body Size (mil/mm)**	14 x 14 mm
Package Weight – Site 1	B1: 569.9900 mg B2: 660.0100 mg	**Package Weight – Site 2**	B1: 661.0004 mg B2: 658.6038 mg
Package Weight – Site 3	660.0100 mg		

SUMMARY

The 100L-TQFP package is qualified at three assembly sites. Packages from different assembly sites may have different material composition. Cypress Ordering Part Numbers containing an “X” (e.g. CY7C1328G-133A**X**I, CY2308S**X**C-1HT) meet the Directive 2002/95/EC (RoHS) requirement.

ASSEMBLY Site 1 – Cypress Manufacturing Limited (CML)
Package Qualification Report # 040806, 052805, 062603, 112302 (See Note 1)

I. DECLARATION OF PACKAGED UNITS

A. BANNED SUBSTANCES

Materials from Level A of the EIA/JIG/JGPSSI/EICTA Material Composition Declaration Guide and EU RoHS. Listed in the table below are materials that are neither contained nor intentionally added to this product.

Substances / Compounds	Weight by mg	PPM	Analysis Report (Note 2)
Cadmium and Cadmium Compounds	0	< 5.0	CoA-AZ100-CML
Hexavalent Chromium and its Compounds	0	< 5.0	
Lead and Lead Compounds	0	< 5.0	
Mercury and Mercury Compounds	0	< 5.0	
Polybrominated Biphenyls (PBB)	0	< 5.0	
Polybrominated Diphenylethers (PBDE)	0	< 5.0	
Asbestos	0	0	As per MSDS
Azo colorants	0	0	As per MSDS
Ozone Depleting Substances	0	0	As per MSDS
Polychlorinated Biphenyls (PCBs)	0	0	As per MSDS
Polychlorinated Napthalenes	0	0	As per MSDS
Radioactive Substances	0	0	As per MSDS
Shortchain Chlorinated Paraffins	0	0	As per MSDS
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	0	0	As per MSDS
Tributyl Tin Oxide (TBTO)	0	0	As per MSDS
Formaldehyde	0	0	As per MSDS

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

B. MATERIAL COMPOSITION (Note 3)

B1: NiPdAu with Standard Mold Compound

Material	Purpose of Use	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogeneous	PPM	%Weight of Substance per package
Leadframe	Base Material	Cu	7440-50-8	39.7595	96.2000%	69,755	6.9755
		Mg	7439-95-4	0.2686	0.6500%	471	0.0471
		Si	7440-21-3	0.0620	0.1500%	109	0.0109
		Ni	7440-02-0	1.2399	3.0000%	2,175	0.2175
Lead Finish	External Plating	Ni	7440-02-0	0.1930	96.5200%	339	0.0339
		Pd	7440-05-3	0.0035	1.7400%	6	0.0006
		Au	7440-57-5	0.0035	1.7400%	6	0.0006
Die Attach	Adhesive	Ag	7440-22-4	0.8300	78.3000%	1,456	0.1456
		Bismaleimide	----------------	0.1200	11.3200%	211	0.0211
		Polymer	----------------	0.0600	5.6600%	105	0.0105
		Methacrylate	----------------	0.0200	1.8900%	35	0.0035
		Acylate ester	----------------	0.0200	1.8900%	35	0.0035
		Organic Peroxide	----------------	0.0100	0.9400%	17	0.0017
Die	Circuit	Si	7440-21-3	14.9500	100.0000%	26,229	2.6229
Wire	Interconnect	Au	7440-57-5	3.3400	100.0000%	5,860	0.5860
Mold Compound	Encapsulation	SiO_2	60676-86-0	448.0168	88.0000%	786,008	78.6008
		Epoxy Resin	----------------	25.4555	5.0000%	44,660	4.4660
		Phenol Resin	----------------	25.4555	5.0000%	44,660	4.4660
		Brominated Epoxy Resin	----------------	4.0729	0.8000%	7,146	0.7146
		Antimony Trioxide	1309-64-4	2.0364	0.4000%	3,573	0.3573
		Others	----------------	4.0729	0.8000%	7,146	0.7146

Package Weight (mg): 569.9900 **% Total: 100.0000**

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

B2: NiPdAu with Green Mold Compound

Material	Purpose of Use	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogeneous	PPM	%Weight of Substance per package
Leadframe	Base Material	Cu	7440-50-8	140.7791	96.2000%	213,298	21.3298
		Si	7440-21-3	0.9512	0.6500%	1,441	0.1441
		Mg	7439-95-4	0.2195	0.1500%	333	0.0333
		Ni	7440-02-0	4.3902	3.0000%	6,652	0.6652
Lead Finish	External Plating	Ni	7440-02-0	3.5326	96.5200%	5,352	0.5352
		Pd	7440-05-3	0.0637	1.7400%	96	0.0096
		Au	7440-57-5	0.0637	1.7400%	96	0.0096
Die Attach	Adhesive	Ag	7440-22-4	2.0320	80.0000%	3,079	0.3079
		Bismaleimide	----------------	0.2286	9.0000%	346	0.0346
		Polymer	----------------	0.1270	5.0000%	192	0.0192
		Methacrylate	----------------	0.0508	2.0000%	77	0.0077
		Acylate ester	----------------	0.0508	2.0000%	77	0.0077
		Organic Peroxide	----------------	0.0508	2.0000%	77	0.0077
Die	Circuit	Si	7440-21-3	35.4700	100.0000%	53,742	5.3742
Wire	Interconnect	Au	7440-57-5	5.0700	100.0000%	7,682	0.7682
Mold Compound	Encapsulation	SiO_2	60676-86-0	415.5677	89.0000%	629,638	62.9638
		Phenol Resin	----------------	23.3465	5.0000%	35,373	3.5373
		Epoxy Resin	----------------	28.0158	6.0000%	42,448	4.2448

Package Weight (mg): 660.0100 **% Total: 100.0000**

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

ASSEMBLY Site 2: Advanced Semiconductor Engineering Taiwan (ASET)
Package Qualification Report # 034101, 120201 (Note 1)

I. DECLARATION OF PACKAGED UNITS

A. BANNED SUBSTANCES

Materials from Level A of the EIA/JIG/JGPSSI/EICTA Material Composition Declaration Guide and EU RoHS. Listed in the table below are materials that are neither contained nor intentionally added to this product.

Substances / Compounds	Weight by mg	PPM	Analysis Report (Note 2)
Cadmium and Cadmium Compounds	0	< 5.0	CoA-AZ100-ASET
Hexavalent Chromium and its Compounds	0	< 5.0	
Lead and Lead Compounds	0	< 5.0	
Mercury and Mercury Compounds	0	< 5.0	
Polybrominated Biphenyls (PBB)	0	< 5.0	
Polybrominated Diphenylethers (PBDE)	0	< 5.0	
Asbestos	0	0	As per MSDS
Azo colorants	0	0	As per MSDS
Ozone Depleting Substances	0	0	As per MSDS
Polychlorinated Biphenyls (PCBs)	0	0	As per MSDS
Polychlorinated Napthalenes	0	0	As per MSDS
Radioactive Substances	0	0	As per MSDS
Shortchain Chlorinated Paraffins	0	0	As per MSDS
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	0	0	As per MSDS
Tributyl Tin Oxide (TBTO)	0	0	As per MSDS
Formaldehyde	0	0	As per MSDS

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

B. MATERIAL COMPOSITION (Note 3)

B1: Using Gold Wire

Material	Purpose of Use	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogeneous	PPM	%Weight of Substance per package
Leadframe	Base Material	Cu	7440-50-8	123.5354	92.8000%	186,892	18.6892%
		Ni	7440-02-0	3.8339	2.8800%	5,800	0.5800%
		Si	7440-21-3	0.8653	0.6500%	1,309	0.1309%
		Mg	7439-95-4	0.1997	0.1500%	302	0.0302%
		Ag	7440-22-4	4.6858	3.5200%	7,089	0.7089%
Lead Finish	External Plating	Pure Sn	7440-31-5	20.9500	100.0000%	31,694	3.1694%
Die Attach	Adhesive	Ag	7440-22-4	2.5802	73.3000%	3,903	0.3903%
		Epoxy Resin	--------------------	0.7300	20.7400%	1,104	0.1104%
		Copper	7440-50-8	0.0700	1.9900%	106	0.0106%
		Gamma-Butyrolactone	96-48-0	0.0700	1.9900%	106	0.0106%
		Aromatic-hydrocarbons	--------------------	0.0700	1.9900%	106	0.0106%
Die	Circuit	Si	7440-21-3	20.6900	100.0000%	31,301	3.1301%
Wire	Interconnect	Au	7440-57-5	4.4900	100.0000%	6,793	0.6793%
Mold Compound	Encapsulation	Epoxy Resin	85954-11-6	23.9115	5.0000%	36,175	3.6175%
		Phenol Resin	26834-02-6	19.0814	3.9900%	28,867	2.8867%
		SiO2	60676-86-0	423.2336	88.5000%	640,292	64.0292%
		Aromatic Phosphate	139189-30-3	7.2213	1.5100%	10,925	1.0925%
		Others	--------------------	4.7823	1.0000%	7,235	0.7235%

Package Weight (mg): 661.0004 **% Total: 100.0000**

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

B2: Using Copper Wire

Material	Purpose of Use	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogeneous	PPM	%Weight of Substance per package
Leadframe	Base Material	Cu	7440-50-8	123.5400	92.8000%	187,579	18.7579%
		Ni	7440-02-0	3.8300	2.8800%	5,815	0.5815%
		Si	7440-21-3	0.8600	0.6500%	1,306	0.1306%
		Mg	7439-95-4	0.2000	0.1500%	304	0.0304%
		Ag	7440-22-4	4.6900	3.5200%	7,121	0.7121%
Lead Finish	External Plating	Sn	7440-31-5	20.9500	100.0000%	31,810	3.1810%
Die Attach	Adhesive	Ag	7440-22-4	2.6048	74.0000%	3,955	0.3955%
		Epoxy resin A	9003-36-5	0.1408	4.0000%	214	0.0214%
		Epoxy resin B	Trade Secret	0.2112	6.0000%	321	0.0321%
		Diluent A	Trade Secret	0.1408	4.0000%	214	0.0214%
		Diluent B	Trade Secret	0.2112	6.0000%	321	0.0321%
		Phenolic Hardener	Trade Secret	0.1760	5.0000%	267	0.0267%
		Dicyandiamide	461-58-5	0.0176	0.5000%	27	0.0027%
		Organic peroxide	Trade Secret	0.0176	0.5000%	27	0.0027%
Die	Circuit	Si	7440-21-3	20.6900	100.0000%	31,415	3.1415%
Wire	Interconnect	Copper	7440-50-8	2.0938	100.0000%	3,179	0.3179%
Mold Compound	Encapsulation	Epoxy resin A	Trade Secret	23.9115	5.0000%	36,306	3.6306%
		Epoxy,Cresol Novolac	29690-82-2	23.9115	5.0000%	36,306	3.6306%
		Phenol resin	Trade Secret	23.9115	5.0000%	36,306	3.6306%
		Metal Hydroxide	Trade Secret	23.9115	5.0000%	36,306	3.6306%
		Carbon Black	1333-86-4	1.4347	0.3000%	2,178	0.2178%
		Silica Fused A	60676-86-0	331.8916	69.4000%	503,932	50.3932%
		Silica Fused B	7631-86-9	47.8230	10.0000%	72,613	7.2613%
		Silica,crystalline	14808-60-7	1.4347	0.3000%	2,178	0.2178%

Package Weight (mg): 658.6038 **% Total: 100.0000**

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

II. DECLARATION OF PACKAGING INDIRECT MATERIALS

Type	Material	Lead PPM	Cadmium PPM	Cr VI PPM	Mercury PPM	PBB PPM	PBDE PPM	Analysis Report (Note2)
Tape & Reel	Cover tape	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-COVT-R
	Carrier tape	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-CART-R
	Plastic Reel	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-PLRL-R
Tray	Tray	< 2.0	< 2.0	< 2.0	< 2.0	---------	---------	CoA-TRAY-R
Others	Shielding bag	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-SBAG –R
	Moisture Barrier bag	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-MBBG-R
	Protective Band	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-PROB-R
	Shipping and Inner Box	< 10.0	< 4.0	< 4.0	< 5.0	---------	-----------	CoA-ABOX-R
	Dessicant	< 10.0	< 2.0	< 2.0	< 1.0	< 3.0	< 3.0	CoA-DESS-R
	Bubble Pack	< 2.0	< 2.0	< 2.0	< 2.0	< 100.0	< 90.0	CoA-BUBP-R

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

ASSEMBLY Site 3: Jiangsu Changjiang Electronics Technology (JCET)
Package Qualification Report # 110909, 111817 (See Note 1)

I. DECLARATION OF PACKAGED UNITS

A. BANNED SUBSTANCES

Materials from Level A of the EIA/JIG/JGPSSI/EICTA Material Composition Declaration Guide and EU RoHS. Listed in the table below are materials that are neither contained nor intentionally added to this product.

Substances / Compounds	Weight by mg	PPM	Analysis Report (Note 2)
Cadmium and Cadmium Compounds	0	< 5.0	CoA-AZ100-JCET
Hexavalent Chromium and its Compounds	0	< 5.0	
Lead and Lead Compounds	0	< 5.0	
Mercury and Mercury Compounds	0	< 5.0	
Polybrominated Biphenyls (PBB)	0	< 5.0	
Polybrominated Diphenylethers (PBDE)	0	< 5.0	
Asbestos	0	0	As per MSDS
Azo colorants	0	0	As per MSDS
Ozone Depleting Substances	0	0	As per MSDS
Polychlorinated Biphenyls (PCBs)	0	0	As per MSDS
Polychlorinated Napthalenes	0	0	As per MSDS
Radioactive Substances	0	0	As per MSDS
Shortchain Chlorinated Paraffins	0	0	As per MSDS
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	0	0	As per MSDS
Tributyl Tin Oxide (TBTO)	0	0	As per MSDS
Formaldehyde	0	0	As per MSDS

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

B. MATERIAL COMPOSITION (Note 3)

Material	Purpose of Use	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogeneous	PPM	%Weight of Substance per package
Leadframe	Base Material	Cu	7440-50-8	140.7791	96.2000%	213,298	21.3298
		Si	7440-21-3	0.9512	0.6500%	1,441	0.1441
		Mg	7439-95-4	0.2195	0.1500%	333	0.0333
		Ni	7440-02-0	4.3902	3.0000%	6,652	0.6652
Lead Finish	External Plating	Ni	7440-02-0	3.5326	96.5200%	5,352	0.5352
		Pd	7440-05-3	0.0637	1.7400%	96	0.0096
		Au	7440-57-5	0.0637	1.7400%	96	0.0096
Die Attach	Adhesive	Ag	7440-22-4	2.0320	80.0000%	3,079	0.3079
		Bismaleimide	----------------	0.2286	9.0000%	346	0.0346
		Polymer	----------------	0.1270	5.0000%	192	0.0192
		Methacrylate	----------------	0.0508	2.0000%	77	0.0077
		Acylate ester	----------------	0.0508	2.0000%	77	0.0077
		Organic Peroxide	----------------	0.0508	2.0000%	77	0.0077
Die	Circuit	Si	7440-21-3	35.4700	100.0000%	53,742	5.3742
Wire	Interconnect	Au	7440-57-5	5.0700	100.0000%	7,682	0.7682
Mold Compound	Encapsulation	SiO_2	60676-86-0	415.5677	89.0000%	629,638	62.9638
		Phenol Resin	----------------	23.3465	5.0000%	35,373	3.5373
		Epoxy Resin	----------------	28.0158	6.0000%	42,448	4.2448

Package Weight (mg): 660.0100 **% Total: 100.0000**

II. DECLARATION OF PACKAGING INDIRECT MATERIALS

Type	Material	Lead PPM	Cadmium PPM	Cr VI PPM	Mercury PPM	PBB PPM	PBDE PPM	Analysis Report (Note2)
Tape & Reel	Cover tape	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-COVT-R
	Carrier tape	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-CART-R
	Plastic Reel	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-PLRL-R
Tray	Tray	< 2.0	< 2.0	< 2.0	< 2.0	---------	---------	CoA-TRAY-R
Others	Shielding bag	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-SBAG –R
	Moisture Barrier bag	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-MBBG-R
	Protective Band	< 2.0	< 2.0	< 2.0	< 2.0	<5.0	<5.0	CoA-PROB-R
	Shipping and Inner Box	< 10.0	< 4.0	< 4.0	< 5.0	---------	-----------	CoA-ABOX-R
	Dessicant	< 10.0	< 2.0	< 2.0	< 1.0	< 3.0	< 3.0	CoA-DESS-R
	Bubble Pack	< 2.0	< 2.0	< 2.0	< 2.0	< 100.0	< 90.0	CoA-BUBP-R

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

Document History Page

Document Title: 100L - TQFP (14 X 14 MM) PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET
Document Number: 001-04270

Rev.	ECN No.	Orig. of Change	Description of Change
**	390185	GFJ	New document
*A	391439	GFJ	Added compliance to Directive 2002/95/EC (RoHS) requirement in the summary. Changed the material composition of Assembly Site 1 and in Assembly Site 2. Added CoA references of indirect materials used in Assembly Site 2.
*B	1318604	MRB	Added reference QTP for Automotive part on Assembly site 1.
*C	1521844	MRB	1. Updated Cypress Logo 2. Added on the material composition the percent weight per homogeneous material and weight of substance 3. Updated and added Lead, Cr+VI, PBB and PBDE on the Declaration of Packaging/Indirect Materials. 4. Added note 4: the package were based on Engineering calculation and performed on a package family basis. 5. Deleted Declaration of Packaging/Indirect Materials on Assembly site 1.
*D	2567367	HLR	Added CAS number of Antimony Trioxide and Silver. DCon: Replaced from CML to WEB in the distribution list.
*E	2737814	MAHA	Added the following for assembly site 1: 1. Package weight for B2 2. Reference QTP # 062603 3. Table B2: NiPdAu with Green Mold Compound
*F	3040395	HLR	Changed the composition of Leadrame on Assemby Site1 (B1).
*G	3219033	REYD	Added Assembly Site 3 – JCET
*H	3340834	CMG	Added QTP# 111817 on Assembly Site 3 – JCET
*I	3400881	CMG	Revised Summary statement – changed package is qualified from "at two assembly sites" to "at three assembly sites" Added QTP# 112302 on Assembly Site 1
*J	3645691	COPI	Added PMDD B2 for assembly site 2 – ASE Taiwan Copper wire qualification under QTP # 120201.
*K	3767019	HLR	Updated the material compositions of Assembly Site 1, Site 2.B1 and Site 3 to reflect 4 decimal places on values.

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

Rev.	ECN No.	Orig. of Change	Description of Change
*L	4031297	YUM	Added Assembly site name in the Assembly heading. Changed Assembly code to Assembly Site Name. Removed entire Tube row in the Indirect Materials Section.

Distribution: WEB

Posting: None

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.
Note 2: Report available from Cypress Sales Offices or Distributors.
Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information
Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.